

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD25CN10N G	**Issued**	24. February 2022
MA#	MA005700259		
Package	PG-TO252-3-313	**Weight***	319.64 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.969	0.93	0.93	9290	9290
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		461	
	non noble metal	copper	7440-50-8	147.096	46.02	46.08	460196	460795
wire	non noble metal	aluminium	7429-90-5	2.656	0.83	0.83	8310	8310
encapsulation	inorganic material	zincoxide	1314-13-2	1.393	0.44		4357	
	miscellaneous	miscellaneous	-	6.963	2.18		21783	
	plastics	epoxy resin	-	20.888	6.53		65349	
	inorganic material	silicondioxide	60676-86-0	110.011	34.42	43.57	344173	435662
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11701	11701
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4444	4455
solder	non noble metal	tin	7440-31-5	0.062	0.02		194	
	noble metal	silver	7440-22-4	0.078	0.02		243	
	non noble metal	lead	7439-92-1	2.965	0.93	0.97	9275	9712
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59997	60075
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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